L Number	Hits	Search Text	DB	Time stamp
3	334	(increas\$3 rais\$3) with height with solder	USPAT	2004/08/20 11:41
4	26	(increas\$3 rais\$3) with height with solder with material	USPAT	2004/08/20
5	5	((semi\$1conductor adj laser) near3 (plural\$3 multiple several)) and	USPAT	2004/08/20 14:12
		(((integrated mono\$1lithic\$4) with (photodetect\$3 detect\$3) with (laser		
		((light radiation) adj (source emit\$4)))) same (tracking near3 (signal error detection)) same (focus\$4 near3 (signal		
9	957	error detection))) 369/\$7.ccls. and ((focus\$4 near3 (signal error)) same (track\$3 near3 (error	USPAT	2004/08/20 17:11
10	186	signal)) same (amplifier)) 369/\$7.ccls. and ((focus\$4 near3 (signal error)) same (track\$3 near3 (error	USPAT	2004/08/20 17:13
		<pre>signal)) same (amplifier)) and ((plural\$3 multiple second) near3 (laser ((light radiation) adj (source emit\$4))))</pre>		
11	8	369/\$7.ccls. and ((focus\$4 near3 (signal error)) same (track\$3 near3 (error	USPAT	2004/08/20 17:14
		signal)) same (amplifier) same ((arithmatic arithmetic) same circuit)) and ((plural\$3 multiple second) near3 (laser ((light radiation) adj (source		
12	5	emit\$4)))) 369/\$7.ccls. and ((focus\$4 near3 (signal error)) same (track\$3 near3 (error	USPAT	2004/08/20 17:17
		signal)) same (amplifier) same ((arithmatic arithmetic) adj circuit)) and ((plural\$3 multiple second) near3 (laser ((light radiation) adj (source		
13	18	emit\$4)))) 369/\$7.ccls. and ((focus\$4 near3 (signal error)) same (track\$3 near3 (error signal)) same (amplifier) same	USPAT	2004/08/20 17:42
16	20	((arithmatic arithmetic) adj circuit)) 369/\$7.ccls. and ((heat adj sink\$3) with (semiconductor adj laser) with substrate)	USPAT	2004/08/20 18:01
21	0	369/\$7.ccls. and (stress\$3 with (relax\$3 reduc\$4 lower\$3 compensat\$3) with	USPAT	2004/08/20 18:02
22	0	(semiconductor adj laser) with substrate) 369/\$7.ccls. and (stress\$3 with (semiconductor adj laser) with substrate)	USPAT	2004/08/20
23	7	369/\$7.ccls. and (stress\$3 with (laser ((light radiation) adj (source emit\$4))) with substrate)	USPAT	2004/08/20 18:04
-	3	tokuda-masahide.in.	US-PGPUB	2004/08/20 11:41
-	31	substrate and mount\$3 and solder\$3 and ((first second plural\$3 multiple) with (electrode contact)) and height	EPO; JPO; IBM_TDB	2004/07/28
-	9	substrate and mount\$3 and solder\$3 and ((first second plural\$3 multiple) with (electrode contact)) and height and	EPO; JPO; IBM_TDB	2004/07/28 11:08
		<pre>((optical semi\$1conductor\$1 laser light) near3 (head pick\$1up (pick adj up) device source))</pre>		
_	1	volume) and 369/\$7.ccls.	USPAT; US-PGPUB	2004/07/28 11:25 2004/07/28
_	720	(solder\$3 with volume) and 369/\$7.ccls.	USPAT; US-PGPUB USPAT;	11:26 2004/07/28
_	/20	(solder\$3 with (height thick\$4)) and (solder\$3 with volume) and ((optical semi\$1conductor\$1 laser light) near3 (head pick\$1up (pick adj up) device	US-PGPUB	11:26
	<u> </u>	source))		l

·				
_	147	<pre>(solder\$3 with (height thick\$4)) and (solder\$3 with volume) and (((optical</pre>	USPAT; US-PGPUB	2004/07/28
		semi\$1conductor\$1 laser light) near3		
		(head pick\$lup (pick adj up) device	*	
		source)) same substrate same mount\$3 same solder\$3)		
_	137	(solder\$3 with (height thick\$4)) and	USPAT;	2004/07/28
		(solder\$3 with volume) and (((optical	US-PGPUB	11:28
		semi\$1conductor\$1 laser light) near3		
		(head pick\$1up (pick adj up) device source)) same substrate same mount\$3 same		
		solder\$3) and (contact electrode)		
-	96	(solder\$3 with (height thick\$4)) and	USPAT;	2004/07/28
		(solder\$3 with volume) and (((optical	US-PGPUB	11:29
		semi\$1conductor\$1 laser light) near3 (head pick\$1up (pick adj up) device		
		source)) with mount\$3) same substrate		
		same solder\$3) and (contact electrode)		
-	75	<pre>(solder\$3 with (height thick\$4)) and (solder\$3 with volume) and ((((optical)))</pre>	USPAT; US-PGPUB	2004/07/28
		semi\$1conductor\$1 laser light) near3	US-FGF0B	11.29
		(head pick\$lup (pick adj up) device		
		source)) with mount\$3 with substrate)		
_	51	same solder\$3) and (contact electrode) (solder\$3 with (height thick\$4)) and	USPAT;	2004/07/28
		(solder\$3 with volume) and (((optical	US-PGPUB	11:29
		semi\$1conductor\$1 laser light) near3		
		(head pick\$1up (pick adj up) device source)) with mount\$3 with substrate with		
		solder\$3) and (contact electrode)		
_	23	(solder\$3 with (height thick\$4)) and	USPAT;	2004/08/02
		<pre>(solder\$3 with volume) and ((((optical semi\$1conductor\$1 laser light) near3</pre>	US-PGPUB	14:17
		semisiconductors: laser light) hears (head pick\$lup (pick adj up) device		
		source)) with mount\$3 with substrate with		
		solder\$3) same (contact electrode))	IICDAM.	1 2004/00/02
-	1	20030147333.pn.	USPAT; US-PGPUB	2004/08/02
_	930	228/180.22.ccls.	USPAT;	2004/08/05
			US-PGPUB	13:50
-	687	228/180.1.ccls.	USPAT; US-PGPUB	2004/08/05
_	775	228/180.21.ccls.	USPAT;	2004/08/05
			US-PGPUB	13:50
-	287	228/245.ccls.	USPAT; US-PGPUB	2004/08/05 13:50
_	380	228/246.ccls.	USPAT;	2004/08/05
			US-PGPUB	13:50
-	758	228/254.ccls.	USPAT;	2004/08/05
_	1412	257/737.ccls.	US-PGPUB USPAT;	13:50 2004/08/05
	1732		US-PGPUB	13:51
-	1318	257/738.ccls.	USPAT;	2004/08/05
1_	5249	228/180.22.ccls. 228/180.1.ccls.	US-PGPUB USPAT;	13:51 2004/08/05
1	3249	228/180.21.ccls. 228/245.ccls.	US-PGPUB	14:06
		228/246.ccls. 228/254.ccls. 257/737.ccls.		
	4500	257/738.ccls. 228/180.22.ccls. 228/180.1.ccls.	USPAT	2004/08/05
1	4520	228/180.22.ccls. 228/180.1.ccls. 228/180.21.ccls. 228/245.ccls.	OSFAI	13:51
		228/246.ccls. 228/254.ccls. 257/737.ccls.]
	37.4	257/738.ccls.	IICDAM.	2004/00/05
-	3742	(228/180.22.ccls. 228/180.1.ccls. 228/180.21.ccls. 228/245.ccls.	USPAT; US-PGPUB	2004/08/05
		228/246.ccls. 228/254.ccls. 257/737.ccls.		
1		257/738.ccls.) and (step\$3 notch\$2		
1_	383	groov\$2) (228/180.22.ccls. 228/180.1.ccls.	USPAT;	2004/08/05
1	383	228/180.21.ccls. 228/245.ccls.	US-PGPUB	14:07
		228/246.ccls. 228/254.ccls. 257/737.ccls.		
1		257/738.ccls.) and (step\$3 notch\$2		
	1	groov\$2) and optical	L	

Search History 8/20/04 6:40:53 PM

-	110	(228/180.22.ccls. 228/180.1.ccls.	USPAT;	2004/08/05
		228/180.21.ccls. 228/245.ccls.	US-PGPUB	14:09
		228/246.ccls. 228/254.ccls. 257/737.ccls.		
		257/738.ccls.) and ((step\$3 notch\$2		
		groov\$2) same optical)		
	242			0004/00/05
_	343	(228/180.22.ccls. 228/180.1.ccls.	USPAT;	2004/08/05
		228/180.21.ccls. 228/245.ccls.	US-PGPUB	14:10
		228/246.ccls. 228/254.ccls. 257/737.ccls.		
		257/738.ccls.) and ((step\$3 notch\$2		
		groov\$2) same (optical laser ((light		
		radiation) adj (source emit\$4))))		
	200		IICDAM.	2004/00/05
-	206	(228/180.22.ccls. 228/180.1.ccls.	USPAT;	2004/08/05
		228/180.21.ccls. 228/245.ccls.	US-PGPUB	15:02
		228/246.ccls. 228/254.ccls. 257/737.ccls.	ł	
		257/738.ccls.) and ((step\$3 notch\$2]
		groov\$2) with (optical laser ((light		
		radiation) adj (source emit\$4))))	ĺ	
_	17	5283446.URPN.	USPAT	2004/08/05
	- /	3203110.0KIN.	031	14:15
	100	//stanca natabea anacidal with /anti1	HEDAT.	1 - 1
-	189	((step\$3 notch\$2 groov\$2) with (optical	USPAT;	2004/08/05
	1	laser ((light radiation) adj (source	US-PGPUB	15:03
	1	emit\$4)))) same substrate same solder\$3		
		same (contact electrode)		
-	189	((stepped step notch notched groove	USPAT;	2004/08/05
		grooved) with (optical laser ((light	US-PGPUB	15:04
		radiation) adj (source emit\$4)))) same		
		substrate same solder\$3 same (contact		
		electrode)		
-	145	((stepped step notch notched groove	USPAT;	2004/08/05
		grooved) with (optical laser ((light	US-PGPUB	15:05
		radiation) adj (source emit\$4)))) same		1
		substrate same solder\$3 same (contact		
		electrode same (align\$4 positioning))		
	142		USPAT;	2004/08/05
_	143	((stepped step notch notched groove	· ·	
		grooved) with (optical laser ((light	US-PGPUB	15:05
		radiation) adj (source emit\$4)))) same		
		substrate same solder\$3 same (contact		1
		electrode same ((align\$4 positioning)		
		with (optical laser ((light radiation)		1
		adj (source emit\$4)))))		
	97	((stepped step notch notched groove	USPAT	2004/08/05
-	"		JULAT	16:46
1	1	grooved) with (optical laser ((light		10.40
]	radiation) adj (source emit\$4)))) same	-	
	1	substrate same solder\$3 same (contact		
]	electrode same ((align\$4 positioning)		
	1	with (optical laser ((light radiation)]
	1	adj (source emit\$4)))))		
_	40	YAMADA-TAKAO.in.	USPAT	2004/08/05
				15:32
	610	VAMADA - TAKAO in	IISDAT.	2004/08/05
-	610	YAMADA-TAKAO.in.	USPAT;	1
			EPO; JPO	15:33
-	51	YAMADA-TAKAO.in. and laser	USPAT;	2004/08/05
	1		EPO; JPO	15:33
-	45	YAMADA-TAKAO.in. and laser and nichia.as.	USPAT;	2004/08/05
1			EPO; JPO	15:40
_	347	(gallium adj nitride) with laser	USPAT	2004/08/05
	37'	'galliam aaj illollao' wron labor		15:40
	1 00	//malling and mituals with larger and	IIGDAM	
-	29	((gallium adj nitride) with laser) and	USPAT	2004/08/05
		solder\$3	1	15:47
-	143	solder with (stud adj bump)	USPAT	2004/08/05
	İ			15:48
-	14	solder with (stud adj bump adj method)	USPAT	2004/08/05
	1			15:48
<u> </u>	5	("5042042" "5987048" "5998232"	USPAT	2004/08/05
1 -	1 5		USPAI	1
		"6015979" "6274891").PN.	L	16:07

•				
Γ-	26		USPAT	2004/08/05
		attaching attached soldering soldered)		17:08
		with (laser ld ((light radiation) adj		
		(source emit\$4))) with (substrate	1	
1		sub\$1mount mount)) same solder\$3 same		
i		electrode same ((align\$4 positioning)		1
		with (optical laser ((light radiation)		
	0	adj (source emit\$4))))		0004/00/05
-		tokukaihei.in.	USPAT;	2004/08/05
		07005700	EPO; JPO	17:08
-	1	07235729.pn.	JPO	2004/08/17
				14:18
-	140900	, ·• · · · · · · · · · · · · · · · · · ·	USPAT	2004/08/17
		with (laser ((light radaition) adj		14:19
		(source emit\$4)))		
-	2359		USPAT	2004/08/17
		with (laser ((light radaition) adj		14:20
		(source emit\$4))) with (mount\$3 solder\$3		1
		disposed) with (substrate)		1
-	706		USPAT	2004/08/17
		with (laser ((light radaition) adj		14:21
		(source emit\$4))) with (mount\$3 solder\$3		1
		disposed) with (substrate) with		1
		semiconductor		İ
-	156		USPAT	2004/08/17
		with (laser ((light radaition) adj		14:29
		(source emit\$4))) with (mount\$3 solder\$3		
ļ		disposed) with (substrate) with		1
		semiconductor with electrode		i
l _	9		USPAT	2004/08/17
Ì		near3 (laser ((light radaition) adj		14:22
		(source emit\$4)))) with (mount\$3 solder\$3		1
1		disposed) with (substrate) with		
		semiconductor) same (electrode near3		
		(plural\$3 multiple))		
	15		USPAT	2004/08/17
-	15	with (laser ((light radaition) adj	USFAI	14:25
		(source emit\$4))) with (mount\$3 solder\$3		14.25
		disposed) with (substrate) with		
		semiconductor) same electrode same		
		1		
	1 22	(solder\$3)	Henam	2004/08/17
-	32		USPAT	2004/08/17
		near2 (laser ((light radaition) adj		14:30
		(source emit\$4)))) with (mount\$3 solder\$3		
		disposed) with (substrate) with		
		semiconductor with electrode		000440045
-	2	(((plural\$3 multiple two several second)	USPAT	2004/08/17
		near2 (laser ((light radaition) adj		14:30
		(source emit\$4)))) with (mount\$3 solder\$3	1	
		disposed) with (substrate) with		
	1	semiconductor) same electrode same		
		solder\$3		